

$V_{RRM} = 650\text{ V}$   
 $I_F(T_c=110^\circ\text{C}) = 6\text{ A}$   
 $Q_C = 20.4\text{ nC}$

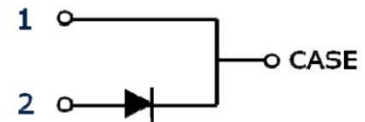
### Features:

- Extremely low reverse current
- No reverse recovery current
- Temperature independent switching
- Positive temperature coefficient on  $V_F$
- Excellent surge current capability
- Low Capacitive charge



### Benefits

- Essentially No switching losses
- System efficiency improvement over Si Diodes
- Increased power density
- Enabling higher switching frequency
- Reduction of Heat Sink Requirements
- System Cost savings due to smaller magnetics
- Reduced EMI



### Applications

- Switch Mode Power Supplies (SMPS)
- Uninterruptable power supplies
- Motor Drivers
- Power Factor Correction

### Package Pin definitions

- Pin1-Cathode
- Pin2-Anode

### Package Parameters

| Part Number | Marking    | Package    |
|-------------|------------|------------|
| B1D06065KF  | B1D06065KF | TO-220F-2L |

**Maximum ratings**

| Symbol        | Parameter                            | Test conditions                                                                    | Value          | Unit                 |
|---------------|--------------------------------------|------------------------------------------------------------------------------------|----------------|----------------------|
| $V_{RRM}$     | Repetitive Peak Reverse Voltage      |                                                                                    | 650            | V                    |
| $V_{RSM}$     | Surge Peak Reverse Voltage           |                                                                                    | 650            | V                    |
| $I_F$         | Continuous Forward Current           | $T_c=25^{\circ}\text{C}$<br>$T_c=110^{\circ}\text{C}$<br>$T_c=150^{\circ}\text{C}$ | 10.6<br>6<br>3 | A                    |
| $I_{FSM}$     | Non-Repetitive Forward Surge Current | $T_c=25^{\circ}\text{C}$ , $t_p=10\text{ms}$ , sine halfwave                       | 44             | A                    |
| $\int i^2 dt$ | $i^2t$ Value                         | $T_c=25^{\circ}\text{C}$ , $t_p=10\text{ms}$                                       | 9.68           | $\text{A}^2\text{S}$ |
| $P_{tot}$     | Power Dissipation                    | $T_c=25^{\circ}\text{C}$<br>$T_c=110^{\circ}\text{C}$                              | 27<br>12       | W                    |
| $T_j$         | Operating junction temperature       |                                                                                    | -55~175        | $^{\circ}\text{C}$   |
| $T_{stg}$     | Storage temperature                  |                                                                                    | -55~135        | $^{\circ}\text{C}$   |

**Thermal Characteristics**

| Symbol       | Parameter                                   | Value |       |      | Unit |
|--------------|---------------------------------------------|-------|-------|------|------|
|              |                                             | Min.  | Typ.  | Max. |      |
| $R_{th(jc)}$ | Thermal resistance from junction to case    |       | 5.394 |      | K/W  |
| $R_{th(ja)}$ | Thermal resistance from junction to ambient |       | 61.94 |      | K/W  |

**Electrical Characteristics**
**Static Characteristics (T<sub>j</sub>=25°C unless otherwise specified)**

| Symbol          | Parameter             | Test conditions                                                                         | Value |             |      | Unit |
|-----------------|-----------------------|-----------------------------------------------------------------------------------------|-------|-------------|------|------|
|                 |                       |                                                                                         | Min.  | Typ.        | Max. |      |
| V <sub>DC</sub> | DC blocking voltage   | T <sub>j</sub> =25°C                                                                    | 650   |             |      | V    |
| V <sub>F</sub>  | Diode forward voltage | I <sub>F</sub> =6A T <sub>j</sub> =25°C<br>I <sub>F</sub> =6A T <sub>j</sub> =175°C     |       | 1.45<br>1.9 |      | V    |
| I <sub>R</sub>  | Reverse current       | V <sub>R</sub> =650V T <sub>j</sub> =25°C<br>V <sub>R</sub> =650V T <sub>j</sub> =175°C |       | 0.05<br>3   |      | μA   |

**Dynamic Characteristics (T<sub>j</sub>=25°C unless otherwise specified)**

| Symbol         | Parameter               | Test conditions                                                                         | Value |                     |      | Unit |
|----------------|-------------------------|-----------------------------------------------------------------------------------------|-------|---------------------|------|------|
|                |                         |                                                                                         | Min.  | Typ.                | Max. |      |
| Q <sub>C</sub> | Total capacitive charge | V <sub>R</sub> =400V T <sub>j</sub> =25°C<br>$Q_C = \int_0^{V_R} C(V)dV$                |       | 20.4                |      | nC   |
| C              | Total Capacitance       | V <sub>R</sub> =1V f=1MHz<br>V <sub>R</sub> =300V f=1MHz<br>V <sub>R</sub> =500V f=1MHz |       | 259<br>39.1<br>38.8 |      | pF   |

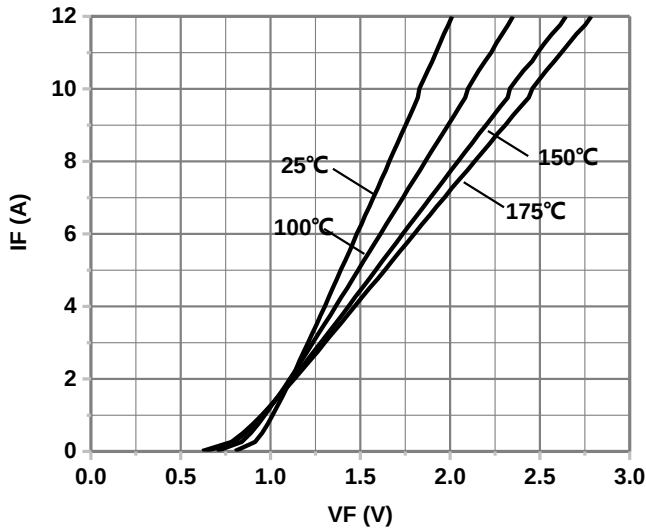


Figure 1. Typical forward characteristics

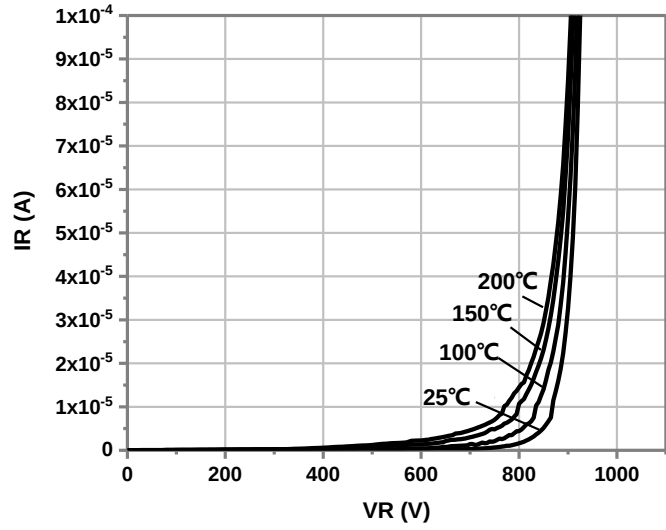


Figure 2. Typical reverse current as function of reverse voltage

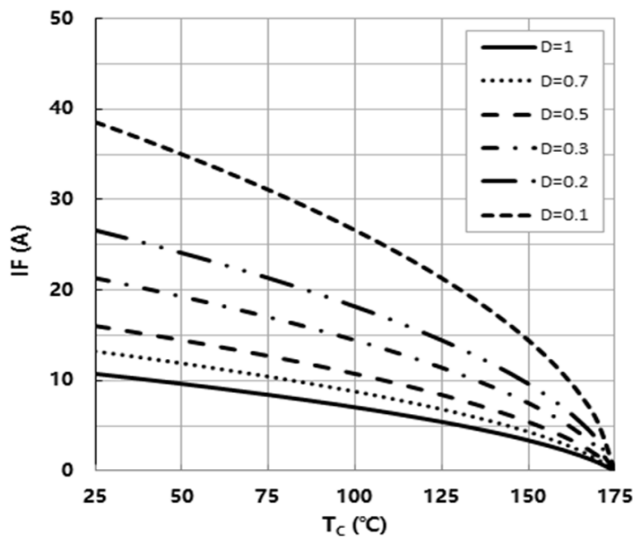


Figure 3. Diode forward current as function of temperature, D=duty cycle

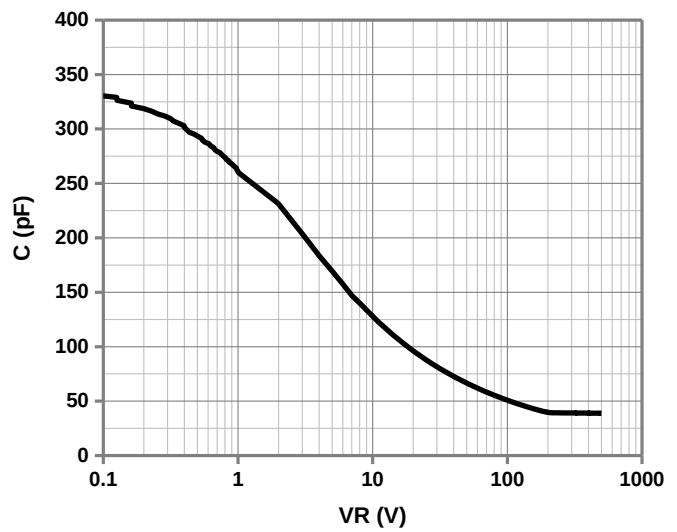


Figure 4. Typical capacitance as function of reverse voltage,  $C=f(V_R)$ ;  $T_j=25^\circ\text{C}$ ;  $f=1\text{ MHz}$

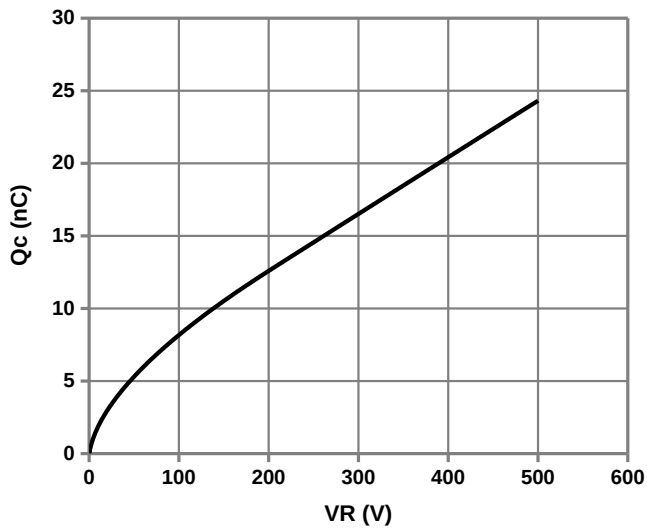


Figure 5. Typical reverse charge as function of reverse voltage

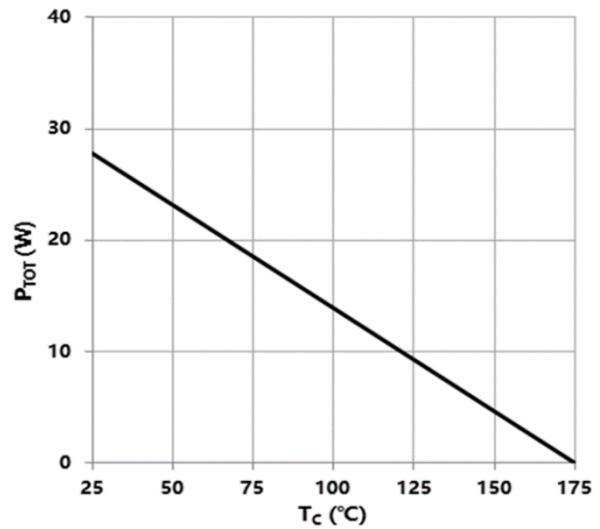


Figure 6. Power dissipation as function of case temperature

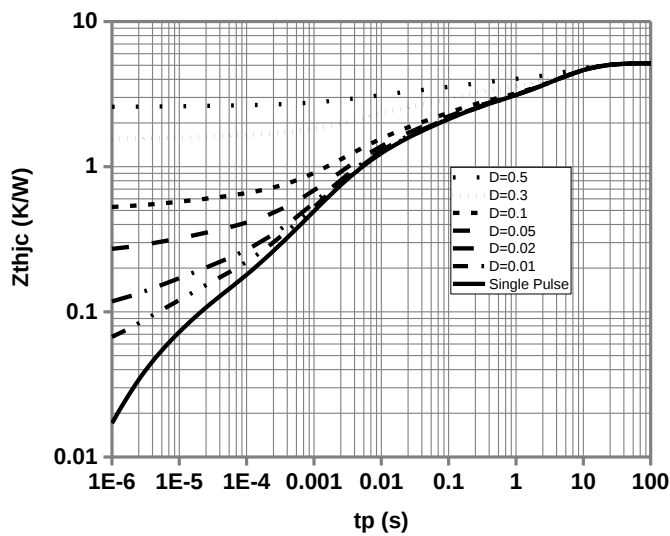
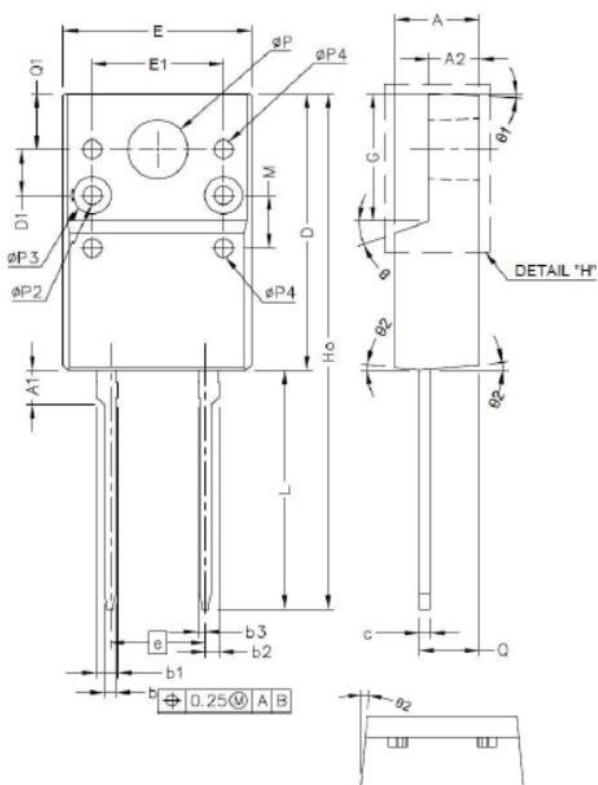


Figure 7. Max. transient thermal impedance,  
 $Z_{th,jc}=f(t)$ , parameter:  $D=t/T$

## Package Dimensions



| SYMBOL | MIN (mm) | MAX (mm) |
|--------|----------|----------|
| A      | 4.30     | 4.93     |
| A1     | 1.80     | 3.90     |
| A2     | 2.34     | 2.90     |
| b      | 0.40     | 0.91     |
| b1     | 1.00     | 1.40     |
| b2     | 0.56     | 0.93     |
| b3     | 0.24     | 0.55     |
| C      | 0.40     | 0.80     |
| D      | 14.70    | 16.07    |
| D1     | 2.50 TYP |          |
| D2     | 2.66 TYP |          |
| e      | 4.83     | 5.33     |
| E      | 9.70     | 10.36    |
| E1     | 7.00 TYP |          |
| G      | 6.50     | 7.10     |
| Ho     | 28 TYP   |          |
| L      | 12.10    | 13.50    |
| L1     |          | 0.50     |
| M      | 2.86 TYP |          |
| ØP     | 2.98     | 3.40     |
| Q      | 3.10     | 3.30     |
| Q1     | 2.70     | 3.50     |
| Ø      | 20° TYP  |          |
| Ø1     | 3° TYP   |          |
| Ø2     | 5° TYP   |          |

**Revision History:****2019-05-15****Preliminary Version**

**BASiC Semiconductor Ltd.**  
**Shenzhen, China**  
**© 2018 BASiC Semiconductor Ltd.**  
**All Rights Reserved.**

**Information**

For further information on technology, delivery terms and conditions and prices, please contact the nearest BASiC Semiconductor Office

**Disclaimer**

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, BASiC semiconductor Ltd. hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.